## **INDIUM CORPORATION WORLDWIDE**

### **Our Goal**

Increase our customers' productivity and profitability through the design, application, and service of advanced materials.

## **Markets Served**



# **PRODUCTS FOR LASER AND OPTICAL** PACKAGING

#### **Indium Corporation**

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is the leading solder and thermal innovator and supplier for laser and optical applications.



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## **HIGH- AND LOW-TEMPERATURE SOLDER**

#### HERMETIC SEALING AND COMPONENT BONDING **IN LASER PACKAGES**

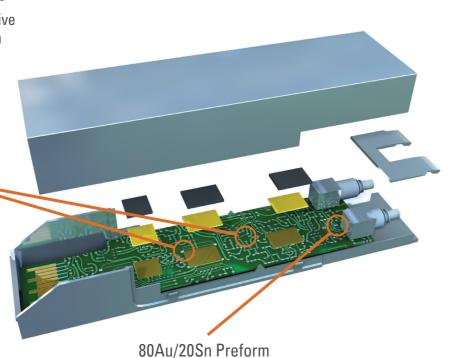
	Attributes	Alloys	Temperature
Gold-Based Alloys	<ul> <li>Strong bond strength</li> <li>Excellent corrosion and oxidation resistance</li> <li>Good thermal and electrical transfer at the braze joint</li> </ul>	Indalloy®182 (80Au/20Sn)	280°C Eutectic
		Indalloy®183 (88Au/12Ge)	356°C Eutectic
		Indalloy <sup>®</sup> 178 (82Au/18In)	Solidus 451°C/Liquidus 485°C
		Indalloy®195 (80Au/20Cu)	891°C Eutectic
		Braze Indalloy®B955 (50Au/50Cu)	Solidus 955°C/Liquidus 970°C
		Braze Indalloy®B9902 (65Cu/35Au)	Solidus 990°C/Liquidus 1,010°C
		Indalloy <sup>®</sup> 200 (100Au)	1,064°C Eutectic
Silver-Based	High thermal and electrical conductivity	Braze Indalloy®B6851 (63Ag/27Cu/10In)	Solidus 685°C/Liquidus 730°C
Alloys	• Capillaries very well into joints	Indalloy®193 (72Ag/28Cu)	780°C Eutectic
	• Holds up well in applications with lots of stress and with CTE mismatches	Braze Indalloy®B962 (99.99Ag)	962°C Eutectic
Tin-Based	• Lead-free	SAC305 Indalloy <sup>®</sup> 256 (96.5Sn/3Ag/.5Cu)	Solidus 217°C /Liquidus 220°C
Alloys	• Excellent wetting characteristics	Indalloy <sup>®</sup> 121 (96.5Sn/3.5Ag)	221°C Eutectic
- 1 -		Indalloy <sup>®</sup> 259 (90Sn/10Sb)	Solidus 243°C /Liquidus 257°C
Indium-Based Alloys	• Typically soft and ductile • Good wettability on many surfaces	Indalloy <sup>®</sup> 4 (100In)	157°C Eutectic
		Indalloy®1E (52In/42Sn)	118°C Eutectic
		Indalloy®290 (97In/3Ag)	143°C Eutectic

## **SFP TRANSCEIVER PACKAGES**

#### Ultra-thin 80Au/20Sn Preforms for **Semiconductor Laser Die Applications**

Indium Corporation's advancements give us the ability to manufacture ultra-thin preforms. These thin preforms add in thermal transfer to keep the die cool for a consistent laser performance.

Indium Corporation offers a variety of SAC alloys in preforms and solder pastes to temperature and performance requirements.



## **OPTICAL PACKAGES**

Laser semiconductor dies produce a lot of heat and 80Au/20Sn preforms are commonly used for good thermal transfer and creep resistance.

Indium Corporation's SAC305 solder preforms and paste are a good option • for component bonding in the package.

#### **Thermal Interface Materials**

- Pure indium preforms for solderingceramic tabs to baseplate also enable thermal transfer.
- Heat-Spring<sup>®</sup> is a compressible thermal interface material that is placed between the package baseplate and the end-user substrate.

### MOST COMMON THERMAL INTERFACE MATERIALS

	Thermal Conductivity (W/mK)	Maximum Operating Temperature	Minimum Pressure	Thermal Resistance at 100psi (cm²-°C/W)
99.99ln	86	130°C	40psi	0.0514 @ 0.004"
52In/48Sn	40	90°C	40psi	0.0390 @ 0.004"
Sn+	73	200°C	100psi	0.4961 @ 0.008"
HSMF	4.5	200°C	10psi	0.4156 @ 0.010"

## **LASER DIODE PACKAGES**

	Indalloy <sup>®</sup> /Temperature (Highest to Lowest)	
193	(72Ag/28Cu) 780°C	
184	(96.8Au/3.2Si) 363°C	
183	(88Au/12Ge) 356°C	
151	(92.5Pb/5Sn/2.5Ag) 298-305°C	
182	(80Au/20Sn) 280°C	
259	(90Sn/10Sb) 243–257°C	
121	(96.5Sn/3.5Ag) 221°C	
256	(96.5Sn/3Ag/0.5Cu) 217-220°C	
106	(63Sn/37Pb) 183°C	
290	(97In/3Ag) 143°C	
282	(57Bi/42Sn/1Ag) 139-140°C	
281	(58Bi/42Sn) 138°C	
1E	(52In/48Sn) 118°C	





